

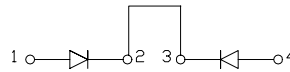
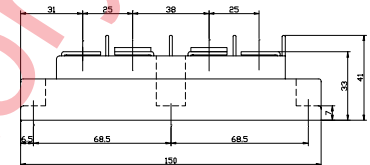
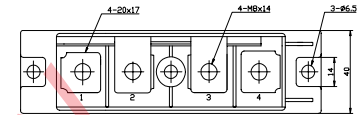
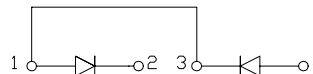
DIODE MODULE 250A/1200,1600V

PC25012, PC25016
PD25012, PD25016
FEATURES

- * Isolated Base
- * Dual Diodes Cathode Common and Cascaded Circuit
- * High Surge Capability
- * UL Recognized, File No. E187184

TYPICAL APPLICATIONS

- * Rectified For General Use

OUTLINE DRAWING
PC

PD

Maximum Ratings

Approx Net Weight:530g

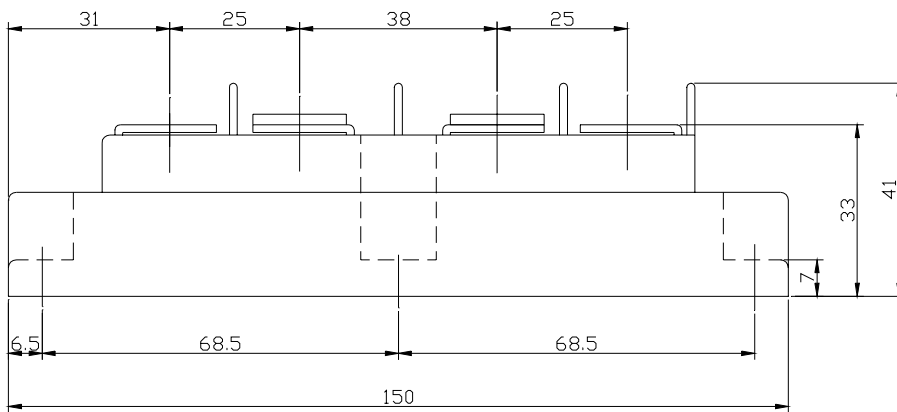
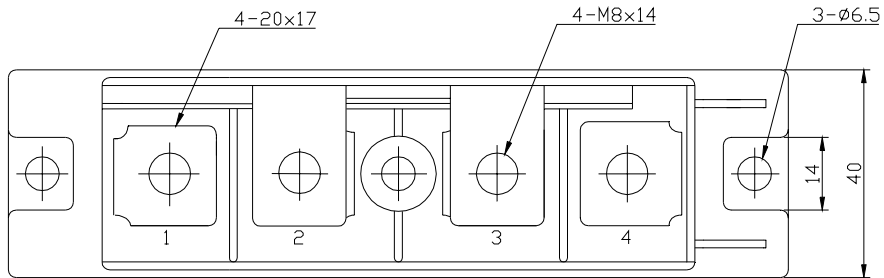
| Parameter | Symbol | Type / Grade | | Unit |
|-------------------------------------|-----------|--------------|------------|------|
| | | PC/D25012 | PC/PD25016 | |
| Repetitive Peak Reverse Voltage | V_{RRM} | 1200 | 1600 | V |
| Non Repetitive Peak Reverse Voltage | V_{RSM} | 1300 | 1700 | |

| Parameter | Symbol | Conditions | Max Rated Value | Unit | |
|--------------------------------------|---------------|---|-----------------|----------------------|-----|
| Average Rectified Output Current | $I_{O(AV)}$ | 50Hz Half Sine Wave condition $T_c=68^\circ\text{C}$ | 250 | A | |
| RMS Forward Current | $I_{F(RMS)}$ | | 390 | A | |
| Surge Forward Current | I_{FSM} | 50 Hz Half Sine Wave, 1cycle Non-repetitive | 5000 | A | |
| I Squared t | I^2t | 2msec to 10msec | 125000 | A^2s | |
| Operating Junction Temperature Range | T_{jw} | | -40 to +150 | $^\circ\text{C}$ | |
| Storage Temperature Range | T_{stg} | | -40 to +125 | $^\circ\text{C}$ | |
| Isolation Voltage | Viso | Base Plate to Terminals, AC1min | 2000 | V | |
| Mounting torque | Case mounting | Ftor | M6 Screw | 2.5 to 3.5 | N.m |
| | Terminals | | M8 Screw | 9.0 to 10.0 | |

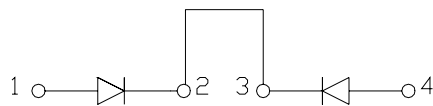
Electrical • Thermal Characteristics

| Characteristics | Symbol | Test Conditions | Max. | Unit |
|----------------------|---------------|---|------|---------------------------|
| Peak Reverse Current | I_{RM} | $V_{RM} = V_{RRM}$, $T_j = 125^\circ\text{C}$ | 30 | mA |
| Peak Forward Voltage | V_{FM} | $I_{FM} = 800\text{A}$, $T_j = 25^\circ\text{C}$ | 1.35 | V |
| Thermal Resistance | $R_{th(j-c)}$ | Junction to Case | 0.18 | $^\circ\text{C}/\text{W}$ |
| | $R_{th(c-f)}$ | Base Plate to Heat Sink with Thermal Compound | 0.1 | |

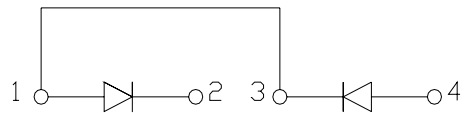
PC/D2501x OUTLINE DRAWING (Dimensions in mm)



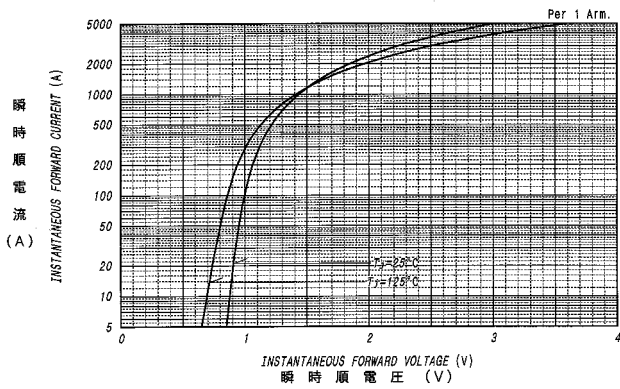
PC



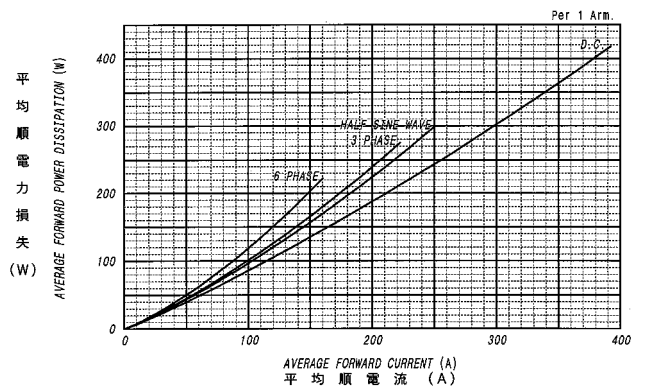
PD



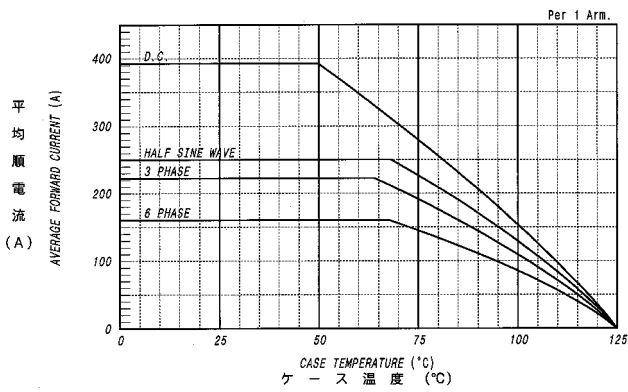
順電圧特性
FORWARD CURRENT VS. VOLTAGE



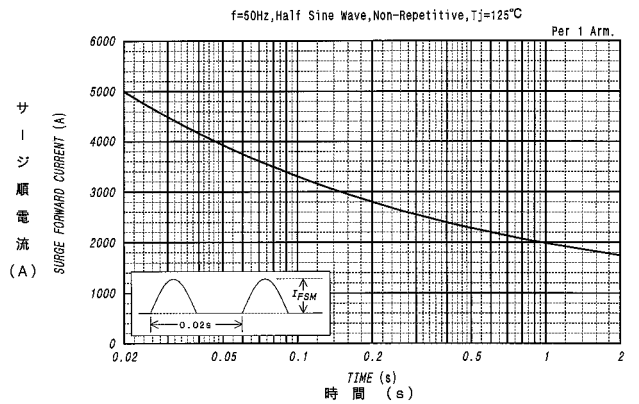
平均順電力損失特性
AVERAGE FORWARD POWER DISSIPATION



平均順電流 - ケース温度定格
AVERAGE FORWARD CURRENT VS. CASE TEMPERATURE



サージ順電流定格
SURGE CURRENT RATINGS



過渡熱抵抗特性
MAXIMUM TRANSIENT THERMAL IMPEDANCE
Junction to Case

